

CLAIMS

What is claimed is:

1. A structure, comprising:

an electrically conducting pattern on at least one of two substrates to
5 be combined with the other of the two substrates via a seal,
wherein said conducting pattern in a region of the seal for attaching the
two substrates is at least partially transmissive to radiation required for curing
said seal under said pattern to affix said two substrates.

2. The structure of claim 1, wherein said transmissive material comprises
10 indium tin oxide (ITO).

3. The structure of claim 1, wherein said transmissive material comprises
indium zinc oxide (IZO).

4. The structure of claim 1, wherein said transmissive material comprises
GaInO₃.

15 5. The structure of claim 1, wherein said transmissive material comprises a
transmissive electrode material in the region containing the seal, thereby
preventing current carrying lines extending from an interior of the structure to
an exterior of the structure from causing shadowing.

6. The structure of claim 1, wherein said seal comprises a photolytically-activated seal.

7. The structure of claim 1, wherein said seal is photolytically activated to cause said seal to cure.

5 8. The structure of claim 1, wherein said conducting lines include metal lines leading from a transistor to a peripheral region of one of said substrates at which said seal is applied.

9. The structure of claim 8, wherein an array of metal lines is substantially parallel to both an edge surface and a fan-out region of said metal lines.

10 10. The structure of claim 1, wherein said metal lines comprise aluminum.

11. The structure of claim 1, wherein, in predetermined regions of said substrates, line segments of said electrically conducting pattern are altered to become electrically conducting but fabricated from said material that is transmissive to the radiation used for curing said seal.

15 12. The structure of claim 1, wherein said material is patterned in one step to include a portion for an interior of said substrates as well as portions for a peripheral edge thereof.

13. The structure of claim 1, wherein said material is formed so as to have an expanded width compared to metallized portions of a line segment of said conducting pattern in a peripheral region.

14. The structure of claim 1, wherein a line segment of said material is equal
5 in width to that of a metal line of said conducting pattern, and includes a bridge formed of indium tin oxide (ITO), between the metal line.

15. The structure of claim 1, wherein a line segment of said material is equal in width to that of a metal line of said conducting pattern, and includes a bridge formed of indium zinc oxide (IZO), between the metal line.

10 16. The structure of claim 1, wherein a line segment of said material is equal in width to that of a metal line of said conducting pattern, and includes a bridge formed of GaInO_3 , between the metal line.

17. The structure of claim 1, wherein said material comprises a very thin metal film having a thickness under approximately 200\AA .

15 18. A liquid crystal display (LCD) panel, comprising:
first and second substrates coupled together by a seal;
a liquid crystal material formed between said first and second substrates; and

an electrically conducting pattern formed on at least one of said first and second substrates such that said conducting pattern in a region of said seal comprises a material at least transmissive to radiation for curing said seal under said pattern, in at least the region of the seal, to couple said first and second substrates together.

19. A method of forming a liquid crystal display panel, comprising:

forming an electrically conducting pattern on at least one of first and second substrates to be coupled together;

forming a liquid crystal material between said first and second substrates;

coupling together said first and second substrates with a seal;

curing said seal with radiation,

wherein said electrically conducting pattern comprises a material at least transmissive to said radiation for curing in at least a region of the seal.

20. The method of claim 19, wherein said material is patterned in one step to include a portion for an interior of said substrates as well as portions for a peripheral edge thereof.